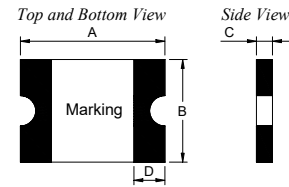


1、 Physical Dimensions(size of 1812)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
MSMD200/16	4.37	4.73	3.07	3.41	0.90	1.30	0.30	T200



2、 Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R1 _{max} (Ω)
					Current(A)	Time(S)			
MSMD200/16	2.00	4.00	16	100	8.0	3.00	1.2	0.020	0.080

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

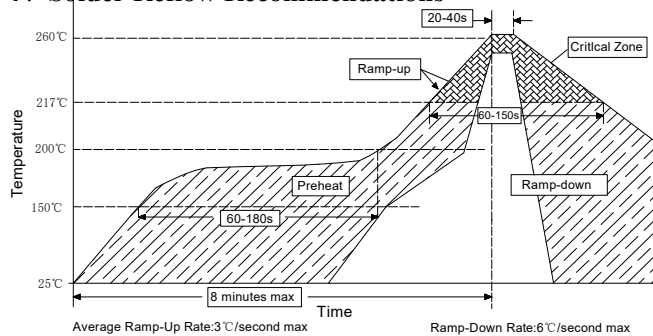
R1_{max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

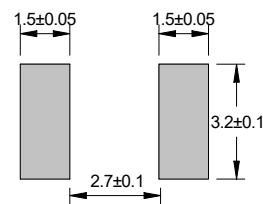
3、 Thermal Derating

MSMD200/16	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	3.08	2.71	2.35	2.00	1.80	1.60	1.50	1.40	1.25
Trip Current(A)	6.16	5.42	4.70	4.00	3.60	3.20	3.00	2.80	2.50

4、 Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、 Package Information

Packing quantity: 1500PCS/Reel

Note: Reel packaging per EIA-481-1 standard